

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A method for making an IC card comprising the steps of:

forming antennal antenna leads and connection leads on an antenna substrate;  
mounting an IC chip on the antenna substrate such that the IC chip is electrically connected to the antenna substrate via the antenna leads and the connection leads;  
mounting an external electrode chip having an external electrode on the antenna substrate such that the external electrode chip is electrically connected to the antenna substrate via the connection leads; and  
disposing a sheath having a hole on the antenna substrate, whereby the external electrode chip is disposed in the hole and the external electrode is exposed at the surface of the sheath.

Claim 2 (Original): The method for making an IC card according to claim 1, wherein, the external electrode chip and the IC chip are mounted on the antenna substrate and then the sheath is disposed on the antenna substrate.

Claim 3 (Original): The method for making an IC card according to claim 1, wherein, the IC chip is mounted on the antenna substrate, the sheath is disposed on the antenna substrate, and then the external electrode chip is mounted on the antenna substrate.

Claim 4 (Original): The method for making an IC card according to claim 1, wherein the external electrode chip has projection terminals on a surface opposite to the surface

having the external electrode, the projection terminals electrically connected to the connection leads.

Claim 5 (Original): An IC card comprising:

an antenna substrate having patterned antenna leads and connection leads for non-contact communication;

a first sheath layer disposed above one of the surfaces of the antenna substrate, the first sheath layer having a hole;

an external electrode chip mounted in the hole, the external electrode chip having an external electrode exposed at the surface of the first sheath layer; and

an IC chip electrically connected to the antenna substrate and the external electrode via the connection leads.

Claim 6 (Original): The IC card according to claim 5, wherein the first sheath layer is bonded to the antenna substrate with an adhesive sheet.

Claim 7 (Original): The IC card according to claim 5 further comprising a second sheath layer disposed on the other surface of the antenna substrate.